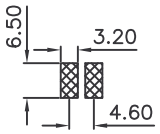
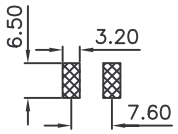
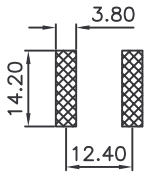


'J' LEAD



'L' LEAD

CHIP SIZE 2220



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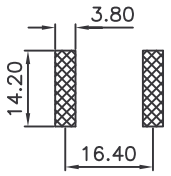
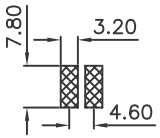
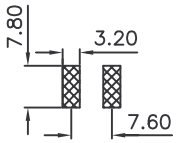


'L' LEAD

CHIP SIZE 5550

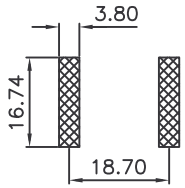


'J' LEAD



'L' LEAD

CHIP SIZE 2225



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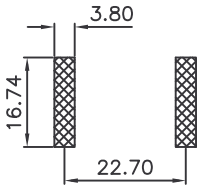
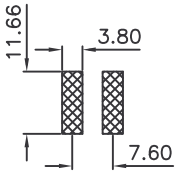
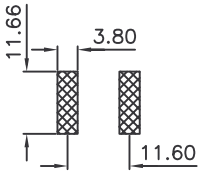


'L' LEAD

CHIP SIZE 8060



'J' LEAD



'L' LEAD

CHIP SIZE 3640

NOTES ON SOLDERING

1) MAX SOLDERING TEMPERATURE 260°C
   SOLDER TYPE Sn62 / Pb FREE SnAgCu OR EQUIVALENTS
   MAX TEMPERATURE RISE 4°C PER SECOND
   SOLDERING TIME 10s MAX
2) FORCED COOLING MUST NOT BE USED.
3) THE SOLDER JOINT SHOULD BE MADE BETWEEN THE HORIZONTAL FOOT AND THE PAD. ANY MENISCUS BETWEEN THE PAD AND THE VERTICAL LEG SHOULD BE KEPT TO A MINIMUM TO PREVENT THE FLEXIBILE LEG FROM BEING STIFFENEND BY THE SOLDER.

CHANGE NOTE No.	DATE	ISSUE No.
4491	05/04/05	2

SCALE N.T.S.

LIMITS UNLESS OTHERWISE STATED
NO DECIMAL PLACES ±0.5
ONE DECIMAL PLACE ±0.2
TWO DECIMAL PLACES ±0.10
DIMENSIONS IN mm U.O.S
THIRD ANGLE PROJECTION

SYFER TECHNOLOGY LTD.,
OLD STOKE ROAD,
ARMINGHALL,
NORWICH. NR14 8SQ
TEL: 01603 723300
TELEX: 97428 SYFER G
TELEFAX: 01603 723301

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DESCRIPTION
RECOMMENDED PAD DIMENSIONS
FOR SURFACE MOUNTED 'J' AND 'L'
LEADED CHIP CAPACITORS

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MATERIAL: N/A
AUTHORISED: S.T. HOPWOOD SIGN:
DATE: 07/05/99 CHECKED:
DRG. No. FSA4/0112/1